



RE711001-LF

- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Without holes
- Hot air leveling (HAL-leadfree) with solder stop mask
- Component print
- PCB for 57 solder practices for implementation into the SMD surface mounted device:

version	quantity
PLCC	20, 68
QFP	84 sq.
TSOP32	1 x
SO14	1 x
SOM16	1 x
SOL20	1 x
SOT23	3 x
SOT143	1 x
SOT89	2 x
SOT233	1 x
DPAK	1 x
Poti.	1 x
Tantal Chip Kond. A	1 x
Tantal Chip Kond. B	1 x
Tantal Chip Kond. C	1 x
Tantal Chip Kond. D	1 x
1206 Chip Kond.	10 x
0805 Chip Kond.	10 x
1210 Chip Kond.	6 x
1812 Chip Kond.	2 x
2220 Chip Kond.	1 x
2308 Melf	2 x
1206 Mini Melf	6 x

- Suitable for Pick & Place
- Size 100 x 140 mm